EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L95	1	"2002018049"	US-PGPUB	OR	ON	2006/09/19 11:36
L94	1642	700/121.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:36
L92	8180	L89 and (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:36
L91	0	(semiconductor with tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:36
L17	3	(CFRDC) and simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:36
L93	805	703/22.ccls.	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L90	1444	L89 and geometric	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L89	19972	(data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L88	740	(FLUENT) and simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L87	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34
L86	1	(tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L85	3	(CFRDC) and simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34

EAST Search History

L84	3	L49 and (converg$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L83	2	L54 and (adjust$6).clm.	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L82	4	L81 and Geometric$4	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L81	19	(US-2003078738-$ or US-20040078319-$ or US-20040102934-$ or (US-20050016947-$).did. or US-5719796-$ or US-6571371-$ or US-6615097-$ or US-6628809-$ or US-6643616-$ or US-6728591-$ or US-6757645-$ or US-6763277-$ or US-6774998-$ or US-6802045-$ or US-6812045-$ or US-6905895-$).did. or (US-5866437-$ or US-20030135302-$ or US-20040078319-$ or US-20050010319-$).did.	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L80	0	(semiconductor and tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L79	127	(ANSYS) with simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L78	0	(processing with tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L77	1	L54 and (nonlinear$3 multivariate).clm.	US-PGPUB	OR	OFF	2006/09/19 11:34
L76	5	L75 and empirical	US-PGPUB	OR	OFF	2006/09/19 11:34
L75	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34
L74	5	L54 and control$6	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L73	9	L49 and (adjust)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L72	1	L49 and (calibration)	US-PGPUB	OR	OFF	2006/09/19 11:34
L71	2	L70 and (rate).clm.	US-PGPUB	OR	OFF	2006/09/19 11:34

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L62	4	(US-20050016947-$).did. or (US-6625497-$ or US-5629877-$ or US-5377116-$ or US-5719796-$ or US-6802045-$ or US-6812045-$).did.	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L61	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34
L60	3	(input with size) with (etch deposition coating lithography (thermal adj annealing)) with (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L59	5	(geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L58	87	geometric and (data parameter) with (etch deposition coating lithography (thermal adj annealing)) with (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L57	29	geometric with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L56	297	(ANSYS) and simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L55	50	("5886906" "5886863" "6031246" "6049661" "6095161" "4268951" "4782253" "5004774" "5546742" "6030491" "6168891" "6178544" "6207630" "6343878" "6443532" "4481049" "4491530" "4500798" "4530587" "4564921" "4581706" "4582683" "4597985" "4602153" "4615782" "4769817" "4792893" "4801713" "4822716" "4842986" "4873661" "4952666" "4969748" "4984902" "4989166" "4999282" "5006717" "5017453" "5059516" "5198520" "5213996" "5243538" "5248956" "5288604" "5312723" "5312724" "5330884" "5331420" "5336752" "5339039").pn.	USPAT	OR	OFF	
L54	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L70	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34
L69	8	L68 and rate	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L68	19	(US-20030078738-$ or US-20040078319-$ or US-20040102934-$ or US-20050016947-$).did. or (US-5719796-$ or US-6571371-$ or US-6615097-$ or US-6628809-$ or US-6643616-$ or US-6728591-$ or US-6757645-$ or US-6763277-$ or US-6774998-$ or US-6802045-$ or US-6812045-$ or US-6905895-$).did. or (US-5866437-$ or US-20030135302-$ or US-20040078319-$ or US-20050010319-$).did.	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L67	3	L54 and (control$6).clm.	US-PGPUB	OR	OFF	2006/09/19 11:34
L66	3	L49 and (nonlinear$3 multivariate)	US-PGPUB	OR	OFF	2006/09/19 11:34
L65	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34
L64	215	(FLUENT) with simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L63	50	("5340697" "5374327" "5382823" "5384289" "5400435" "5406309" "5409547" "5418397" "5427716" "5442644" "5455928" "5459020" "5474884" "5478702" "5490953" "5493501" "5495417" "5511005" "5517140" "5523022" "5558964" "5561612" "5571662" "5593608" "5596695" "5617322" "5619159" "5629877" "5637151" "5650947" "5654904" "5658706" "5663889" "5672468" "5672907" "5684723" "5694325" "5694052" "5699264" "5706200" "5709757" "5712794" "5714678" "5715170" "5725974" "5728514" "5731626" "5736024" "5737242" "5745388").pn.	USPAT	OR	OFF	2006/09/19 11:34

EAST Search History

L41	5	L40 and empirical	US-PGPUB	OR	OFF	2006/09/19 11:34
L40	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34
L39	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34
L38	805	703/22.ccls.	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L37	4	(US-20050016947-$).did. or (US-6625497-$ or US-5629877-$ or US-5377116-$ or US-5719796-$ or US-6802045-$ or US-6812045-$).did.	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L36	50	("5340697" "5374327" "5382823" "5384289" "5400435" "5406309" "5409547" "5418397" "5427716" "5442644" "5455928" "5459020" "5474884" "5478702" "5490953" "5493501" "5495417" "5511005" "5517140" "5523022" "5558964" "5561612" "5571662" "5593608" "5596695" "5617322" "5619159" "5629877" "5637151" "5650947" "5654904" "5658706" "5663889" "5672468" "5672907" "5684723" "5694325" "5694052" "5699264" "5706200" "5709757" "5712794" "5714678" "5715170" "5725974" "5728514" "5731626" "5736024" "5737242" "5745388").pn.	USPAT	OR	OFF	2006/09/19 11:34
L35	50	("5886906" "5886363" "6031246" "6049661" "6095161" "4268951" "4782253" "5004774" "5446742" "6030491" "6168891" "6178544" "6207630" "4343878" "4443532" "4481049" "4491530" "4500798" "4530587" "4564921" "4581706" "4582683" "4597985" "4602153" "4615782" "4769817" "4792893" "4801713" "4822716" "4842986" "4873661" "4952666" "4969748" "4984902" "4989166" "4999282" "5006717" "5017453" "5059516" "5198520" "5213996" "5243538" "5248956" "5288604" "5312723" "5312724" "5330884" "5331420" "5336752" "5339039").pn.	USPAT	OR		2006/09/19 11:34
L34	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34

EAST Search History

L53	163	(FLUENT) and simulat$4 and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L52	6	(emperical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L51	2	(physical with geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L50	0	semiconductor with tool with emperical with model	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L49	19	(US-20030078738-$ or US-20040078319-$ or US-2004102934-$ or US-20050016947-$).did. or (US-5719796-$ or US-6571371-$ or US-6615097-$ or US-6628809-$ or US-6643616-$ or US-6728591-$ or US-6757645-$ or US-6763277-$ or US-6774998-$ or US-6802045-$ or US-6812045-$ or US-6905895-$).did. or (US-5866437-$ or WO-200177979-$ or WO-200277589-$ or US-20030135302-$ or US-20040078319-$ or US-20040007813-$ or US-20050010319-$).did.	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L48	5433	(ANSYS FLUENT CFRDC (Monte adj Carlo)) and simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L47	6	(emperical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L46	1	(tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L45	0	(semiconductor and tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L44	0	(processing with tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L43	0	(semiconductor with tool) and (emperical with model)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L42	0	semiconductor with tool with emperical with model	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34

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L22	163	(FLUENT) and simulat$4 and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L21	127	(ANSYS) with simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L20	215	(FLUENT) with simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L19	1642	700/121.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L18	740	(FLUENT) and simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L16	297	(ANSYS) and simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L15	5433	(ANSYS FLUENT CFRDC (Monte adj Carlo)) and simulat$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L14	3	L3 and (converg$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34

L33	3	(input with size) with (etch deposition coating lithography (thermal adj annealing)) with (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L32	5	(geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L31	2	(physical with geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L30	87	geometric and (data parameter) with (etch deposition coating lithography (thermal adj annealing)) with (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L29	29	geometric with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L28	1444	L26 and geometric	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L27	8180	L26 and (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L26	19972	(data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L25	4	L24 and Geometric$4	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L24	19	(US-20030078738-$ or US-20040078319-$ or US-20040102934-$ or US-2005001694 7-$).did. or (US-5719796-$ or US-6571371-$ or US-6615097-$ or US-6628809-$ or US-6643616-$ or US-6728591-$ or US-6757645-$ or US-6763277-$ or US-6774998-$ or US-6802045-$ or US-6812045-$ or US-6905895-$). did. or (US-5866437-$ or US-20030135302-$ or US-20040078319-$ or US-20050010319-$).did.	US-PGPUB; USPAT	OR		
L23	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34

EAST Search History

L1						
	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34

EAST Search History

L13	9	L3 and (adjust)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:34
L12	1	L3 and (calibration)	US-PGPUB	OR	OFF	2006/09/19 11:34
L11	3	L3 and (nonlinear$3 multivariate)	US-PGPUB	OR	OFF	2006/09/19 11:34
L10	1	L6 and (nonlinear$3 multivariate).clm.	US-PGPUB	OR	OFF	2006/09/19 11:34
L9	2	L6 and (adjust$6).clm.	US-PGPUB	OR	OFF	2006/09/19 11:34
L8	3	L6 and (control$6).clm.	US-PGPUB	OR	OFF	2006/09/19 11:34
L7	5	L6 and control$6	US-PGPUB	OR	OFF	2006/09/19 11:34
L6	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/09/19 11:34
L5	8	L4 and rate	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L4	19	(US-20030078738-$ or US-20040078319-$ or US-20040102934-$ or US-20050016947-$).did. or (US-5719796-$ or US-6571371-$ or US-6615097-$ or US-6628809-$ or US-6643616-$ or US-6728591-$ or US-6757645$ or US-6763277-$ or US-6774998-$ or US-6802045-$ or US-6812045-$ or US-6905895-$).did. or (US-5866437-$ or US-20030135302-$ or US-20040078319-$ or US-20050010319-$).did.	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L3	19	(US-20030078738-$ or US-20040078319-$ or US-20040102934-$ or US-20050016947-$).did. or (US-5719796-$ or US-6571371-$ or US-6615097-$ or US-6628809-$ or US-6643616-$ or US-6728591-$ or US-6757645-$ or US-6763277-$ or US-6774998-$ or US-6802045-$ or US-6812045-$ or US-6905895-$).did. or (US-5866437-$ or WO-200177979-$ or WO-200277589-$ or US-20030135302-$ or US-20040078319-$ or US-20050010319-$).did.	US-PGPUB; USPAT	OR	OFF	2006/09/19 11:34
L2	2	L1 and (rate).clm.	US-PGPUB	OR	OFF	2006/09/19 11:34